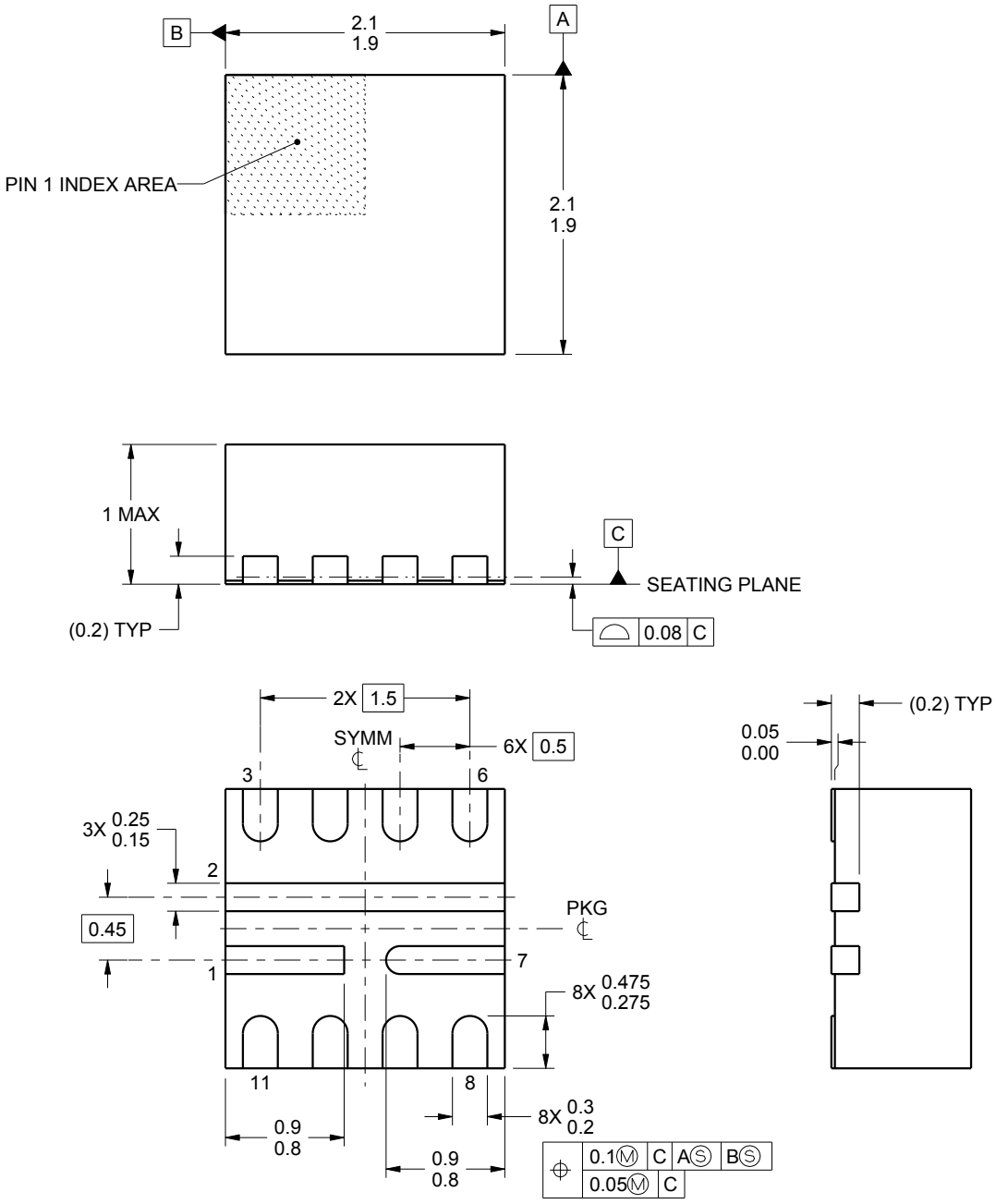
PACKAGE OUTLINE

RWK0011B

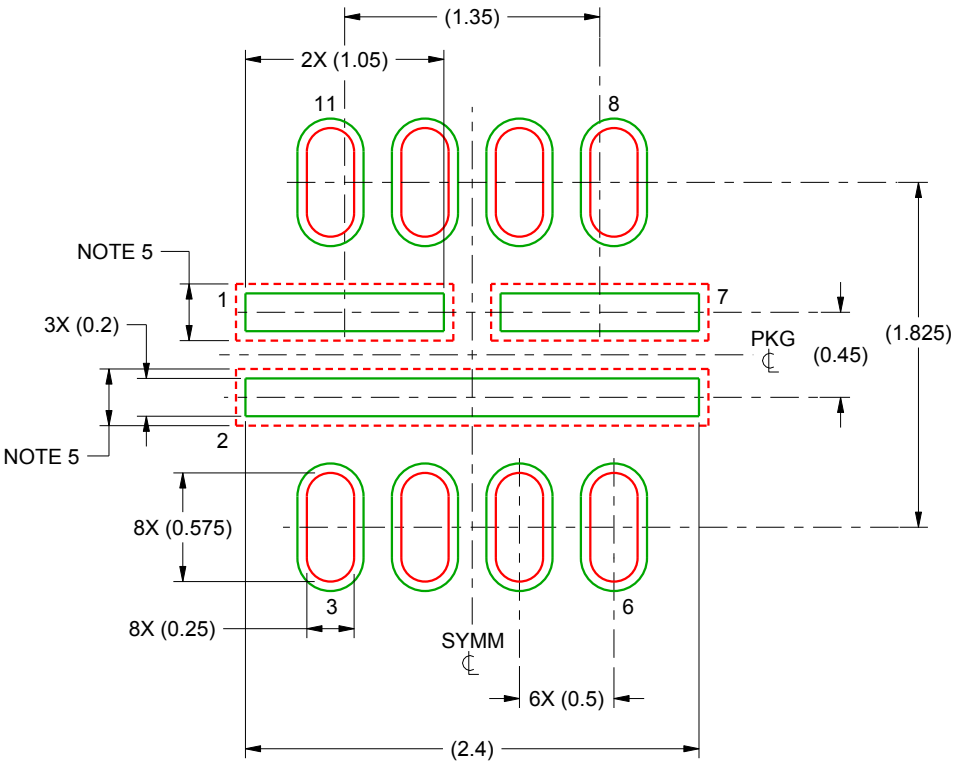
VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

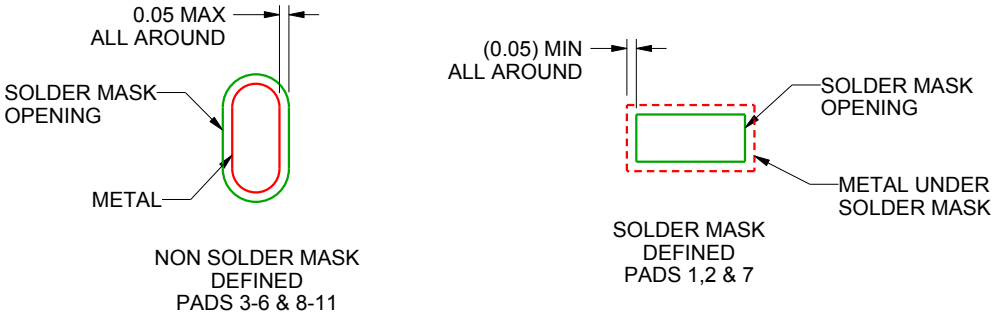


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. Package pin numbers 1, 2, and 7 must be soldered to the printed circuit board for thermal and mechanical performance. Refer to product data sheet for specific thermal pad and via recommendations.



LAND PATTERN EXAMPLE
SCALE:25X



SOLDER MASK DETAILS

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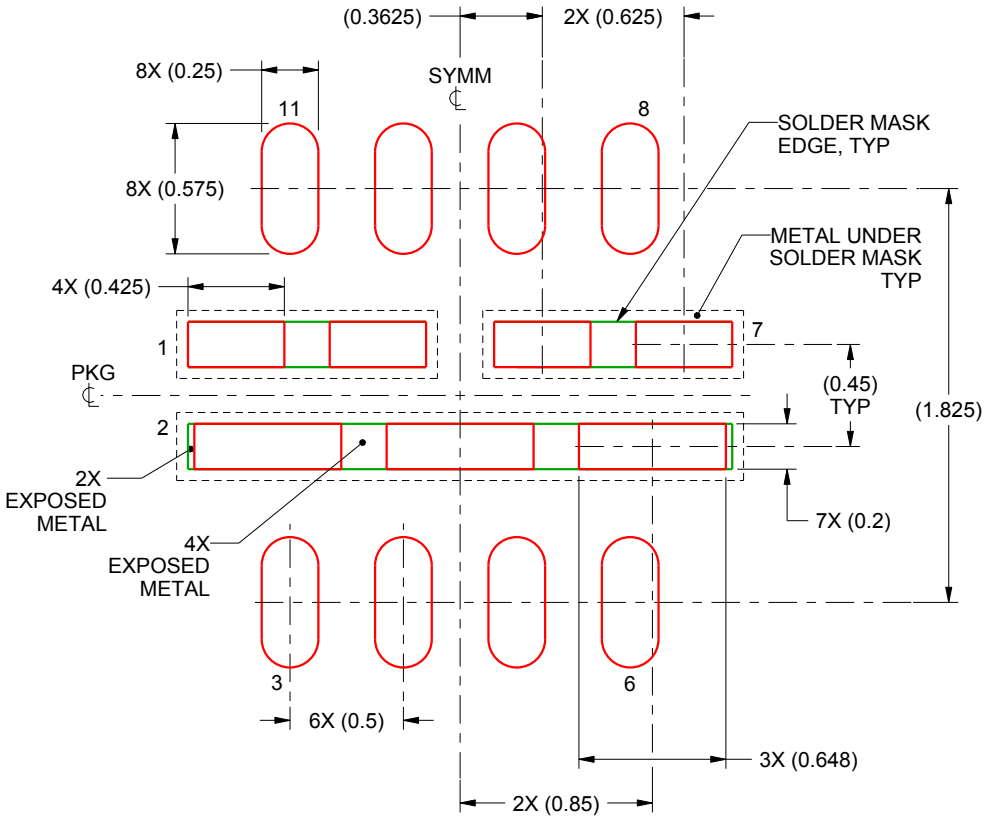
NOTES: (continued)

4. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Size of metal pad may vary due to creepage requirements.



SOLDER PASTE EXAMPLE
BASED ON 0.1 mm THICK STENCIL

PADS 1,2 & 7
81% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:30X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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